

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jun. 21, 2012

Expected First Date Code of Changed Product :1224

Last Date for Shipment of Unchanged Product : Jun. 21, 2012

Description of Change (From) :

6 inch wafer diameter for the detector die component of all listed products as per below list.

Description of Change (To) :

8 inch wafer diameter for the detector die component of all listed products as per list and with fabrication process/ circuit design improvements for all listed products per subgroup A, B and C.

subgroup A :In addition to the core 6 to 8 inch process migration, the FOD060L, HCPL062N, HCPL0637, HCPL0638, HCPL0639 and OI2010 product series will be moving from the CS080CBiH30 fabrication process to the CS080CBiH40 fabrication process. The products will not have change in form, fit or function. There will be no datasheet changes.

subgroup B :In addition to the core 6 to 8 inch process migration, the FOD3180 and FOD3181 product series will be moving from the CS080CBiH30 fabrication process to the CS080CBiH40 fabrication process with a design modification. This design modification includes adding in an anti-shoot through structure. The products will not have change in form, fit or function. There will be no datasheet changes.

subgroup C :In addition to the core 6 to 8 inch process migration, the FOD8001, FOD0721, FOD0720 and FOD0710 product series will have a minor design modification. This design modification includes increasing the internal threshold voltage. The products will not have change in form, fit or function. There will be no datasheet changes.

Reason for Change:

Fairchild Semiconductor is closing the 6" fabrication line and qualifying a 8" fabrication line. This is to increase the production capacity in our wafer fabrication facilities in USA.

In additional, we will migrate/change the fabrication processes/ circuit design used for some affected products. This change will improve the robustness of the products beyond the required specifications. This change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications.

Products incorporating this change may be shipped interchangeably with existing unchanged products. Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Affected Product(s):

4N25M	4N25SM	4N25SR2M
4N25SR2VM	4N25SVM	4N25TVM
4N25VM	4N26M	4N26SM
4N26SR2M	4N26SR2VM	4N26SVM
4N26TVM	4N26VM	4N27M
4N27SM	4N27SR2M	4N27SR2VM
4N27SVM	4N27TVM	4N27VM
4N28M	4N28SM	4N28SR2M
4N28SR2VM	4N28SVM	4N28TVM
4N28VM	4N35M	4N35SM
4N35SR2M	4N35SR2VM	4N35SVM
4N35TVM	4N35VM	4N36M
4N36SM	4N36SR2M	4N36SR2VM
4N36SVM	4N36TVM	4N36VM
4N37M	4N37SM	4N37SR2M
4N37SR2VM	4N37SVM	4N37TVM
4N37VM	4N38M	4N38SR2M
CNY171M	CNY171SM	CNY171SR2M
CNY171SR2VM	CNY171SVM	CNY171TVM
CNY171VM	CNY172M	CNY172SM
CNY172SR2M	CNY172SR2VM	CNY172SVM
CNY172TVM	CNY172VM	CNY173M
CNY173SM	CNY173SR2M	CNY173SR2VM
CNY173SVM	CNY173TVM	CNY173VM
CNY174M	CNY174SM	CNY174SR2M
CNY174SR2VM	CNY174SVM	CNY174TVM
CNY174VM	CNY17F1M	CNY17F1SM
CNY17F1SR2M	CNY17F1SR2VM	CNY17F1SVM
CNY17F1TVM	CNY17F1VM	CNY17F2M
CNY17F2SM	CNY17F2SR2M	CNY17F2SR2VM
CNY17F2SVM	CNY17F2TVM	CNY17F2VM
CNY17F3M	CNY17F3SM	CNY17F3SR2M
CNY17F3SR2M_F132	CNY17F3SR2VM	CNY17F3SVM
CNY17F3TVM	CNY17F3VM	CNY17F4M
CNY17F4SM	CNY17F4SR2M	CNY17F4SR2VM
CNY17F4SVM	CNY17F4TVM	CNY17F4VM
FOD060L	FOD060LR2	FOD0710
FOD0710R2	FOD0720	FOD0720R2
FOD0721	FOD0721R2	FOD2711A
FOD2711AS	FOD2711ASD	FOD2711ASDV

Affected Product(s):

FOD2711ASV	FOD2711ATV	FOD2711AV
FOD2712A	FOD2712AR2	FOD2712AR2V
FOD2712AV	FOD2741AS	FOD2741ASD
FOD2741ASDV	FOD2741ASV	FOD2741ATV
FOD2741AV	FOD2741BS	FOD2741BSD
FOD2741BSDV	FOD2741BSV	FOD2741BTV
FOD2741BV	FOD2742BR2	FOD2742BR2V
FOD2742BV	FOD2743BS	FOD2743BSD
FOD2743BSDV	FOD2743BSV	FOD2743BTV
FOD2743BV	FOD3120	FOD3120S
FOD3120SD	FOD3120SDV	FOD3120SV
FOD3120T	FOD3120TS	FOD3120TSR2
FOD3120TSR2V	FOD3120TSV	FOD3120TV
FOD3120V	FOD3150	FOD3150S
FOD3150SD	FOD3150SDV	FOD3150SV
FOD3150TS	FOD3150TSR2	FOD3150TSR2V
FOD3150TSV	FOD3150TV	FOD3150V
FOD3180	FOD3180ASD	FOD3180S
FOD3180SD	FOD3180SDV	FOD3180SV
FOD3180TV	FOD3180V	FOD3181
FOD3181S	FOD3181SD	FOD3181SDV
FOD3181SV	FOD3181TV	FOD3181V
FOD3182	FOD3182S	FOD3182SD
FOD3182SDV	FOD3182SV	FOD3182TSR2
FOD3182TSR2V	FOD3182TSV	FOD3182TV
FOD3182V	FOD3184	FOD3184S
FOD3184SD	FOD3184SDV	FOD3184SV
FOD3184TSD	FOD3184TSDV	FOD3184TSR2
FOD3184TSR2V	FOD3184TSV	FOD3184TV
FOD3184V	FOD8001	FOD8001R2
FOD8012	FOD8012R2	FODM121
FODM121A	FODM121AR2	FODM121AR2V
FODM121AR4	FODM121AV	FODM121B
FODM121BR2	FODM121BR2V	FODM121BR4
FODM121BV	FODM121C	FODM121CR2
FODM121CR2V	FODM121CV	FODM121GR4
FODM121R2	FODM121R2V	FODM124
FODM124R2	FODM124R2V	FODM2701
FODM2701R2	FODM2701R2V	FODM2701R4
FODM2705	FODM2705R2	FODM2705R2V

Affected Product(s):

FODM2705R2V_5709	FODM2705V	FODM8071
FODM8071R2	FODM8801A	FODM8801AR2
FODM8801B	FODM8801BR2	FODM8801C
FODM8801CR2	H11A1M	H11A1SM
H11A1SR2M	H11A1SR2VM	H11A1SVM
H11A1TVM	H11A1VM	H11AA1M
H11AA1SM	H11AA1SR2M	H11AA1SR2VM
H11AA1SVM	H11AA1TVM	H11AA1VM
H11AA4M	H11AA4SDM	H11AA4SM
H11AA4SR2M	H11AA4SR2VM	H11AA4SVM
H11AA4TVM	H11AA4VM	H11AV1AM
H11AV1AVM	H11AV1M	H11AV1SM
H11AV1SR2M	H11AV1SR2VM	H11AV1SVM
H11AV1VM	H11AXM_5164	H11AXM_5164SR2V
H11AXM_5164SV	H11L1M	H11L1SM
H11L1SR2M	H11L1SR2VM	H11L1SVM
H11L1TVM	H11L1VM	H11L2M
H11L2SM	H11L2SR2M	H11L2SR2VM
H11L2SVM	H11L2TVM	H11L2VM
H11L3M	H11L3SM	H11L3SR2M
H11L3SR2VM	H11L3SVM	H11L3TVM
H11L3VM	H11LXM_5555R2	H11LXM_9114
H11N1M	H11N1SM	H11N1SR2M
H11N1SR2VM	H11N1SVM	H11N1TVM
H11N1VM	H11N2M	H11N2SM
H11N2SR2M	H11N2SR2VM	H11N2SVM
H11N2TVM	H11N2VM	H11SAXM_5598D
HCPL062N	HCPL062NR2	HCPL0637
HCPL0637R2	HCPL0638	HCPL0638R2
HCPL0639	HCPL0639R2	HMA121CR3V_NF098
HMHA2801	HMHA2801A	HMHA2801AR2
HMHA2801AR2V	HMHA2801AV	HMHA2801R2
HMHA2801R2V	HMHA2801V	HMHA281
HMHA281R2	HMHA281R2V	HMHA281V
HMHAA280	HMHAA280R2	HMHAA280R2V
HMHAA280V	MCT2EM	MCT2ESM
MCT2ESR2M	MCT2ESR2VM	MCT2ESVM
MCT2ETVM	MCT2EVM	MOC205R2M
MOC205R2VM	MOC205VM	MOC206M
MOC206R2M	MOC206R2VM	MOC206VM

Affected Product(s):

MOC207R2M	MOC207R2VM	MOC207VM
MOC211M	MOC211R2M	MOC211R2VM
MOC211VM	MOC212M	MOC212R2M
MOC212R2VM	MOC212VM	MOC213M
MOC213R2M	MOC213R2VM	MOC213VM
MOC216M	MOC216R2M	MOC216R2VM
MOC216VM	MOC217R2M F132	MOC256M
MOC256R2M	MOC256R2VM	MOC256VM
MOC8106M	MOC8106SM	MOC8106SR2M
MOC8106SR2VM	MOCD207D2M	MOCD207M F132
MOCD207R2M	MOCD207R2M F132	MOCD207R2VM
MOCD207VM	MOCD208M	MOCD208R2M
MOCD208R2VM	MOCD208VM	MOCD211M
MOCD211R2M	MOCD211R2VM	MOCD211VM
MOCD213M	MOCD213R2M	MOCD213R2VM
MOCD213VM	OI2010	TIL111M
TIL111SM	TIL111SR2M	TIL111SR2VM
TIL111SVM	TIL111TVM	TIL111VM
TIL117M	TIL117SM	TIL117SR2M
TIL117SR2VM	TIL117SVM	TIL117TVM
TIL117VM		

Qualification Plan	Device	Package	Process	No. of Lots
Q20110520	FOD3120	8PW	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/693
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Temperature Op Life Test	100C		1000 hrs	0/231
High Temperature Storage Life	125C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20100529	H11L1M	6PW	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/1124
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Temperature Op Life Test	100C		1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
High Temperature Reverse Bias	100C		1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 hrs	0/231